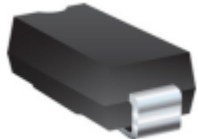


# MATERIAL DECLARATION SHEET



Package Type	SMA (DO-214AC)			
Product Line	TISP Thyristor Surge Protection			
Compliance Date	November 30, 2004			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\	CAS Number	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
				Substances				
1	Encapsulation	Epoxy resin	0.038725	Fused Silica (SiO <sub>2</sub> )	60676-86-0	85.00	47.87470002	56.3232
				Epoxy Resin	93705-66-9	8.00	4.50585412	
				Phenol Resin	26834-02-6	6.50	3.661006472	
				Carbon Black	1333-86-4	0.50	0.281615882	
2	Leadframe	Copper	0.027699	Copper	7440-50-8	99.87	40.23415213	40.2865
				Iron	7439-89-6	0.10	0.040286525	
				Phosphorus	7723-14-0	0.03	0.012085957	
3	Chip	Silicon	0.00139	Silicon	7440-21-3	90.41	1.827792888	2.0215
				Aluminum	7429-90-5	3.18	0.064289143	
				Nickel	02/02/7440	6.12	0.123726274	
				Gold	7440-57-5	0.28	0.005660679	
4	Die Attach	HMP Solder	0.000222	Tin	7440-31-5	5.00	0.01614428	0.3229
				Lead	7439-92-1	92.50	0.298669188	
				Silver	7440-22-4	2.50	0.00807214	
5	Terminal Finish	Matte Sn	0.000719	Tin	7440-31-5	100.00	1.045742128	1.0457
		Total Weight	0.068755					

This Document was updated on: 2020/11/20

Important remarks: 1. It is the responsibility of the user to verify they are accessing the latest version.